

WHAT IS CLAIMED IS:

1. A wafer support plate comprising:
a support surface on which a semiconductor wafer is supported; and
5 a crystal orientation mark which indicates a crystal orientation of the supported semiconductor wafer.
2. A wafer support plate according to claim 1, wherein said crystal orientation mark is formed at an outer-peripheral part of said support surface.
- 10 3. A wafer support plate according to claim 1, wherein said crystal orientation mark is formed on an outer-peripheral side surface of said support surface.
- 15 4. A wafer support plate according to claim 1, wherein said crystal orientation mark is formed by cutting away an outer-peripheral part of said support surface.
- 20 5. A wafer support plate according to any of claims 1 to 4, wherein said wafer support plate is formed of a material selected from the group consisting of glass, metal, ceramics, and synthetic resin.